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Ker et al.

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(54) **ACTIVE DEVICE ARRAY SUBSTRATE
HAVING ELECTROSTATIC DISCHARGE
PROTECTION CAPABILITY**

(75) Inventors: **Ming-Dou Ker**, Hsinchu County (TW);
Chih-Kang Deng, Taipei County (TW)

(73) Assignee: **Chunghwa Picture Tubes, Ltd.**,
Taoyuan (TW)

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(51) **Int. Cl.**
G02F 1/133 (2006.01)

(52) **U.S. Cl.** 361/56; 349/40

(58) **Field of Classification Search** 361/56,
361/111; 349/40

See application file for complete search history.

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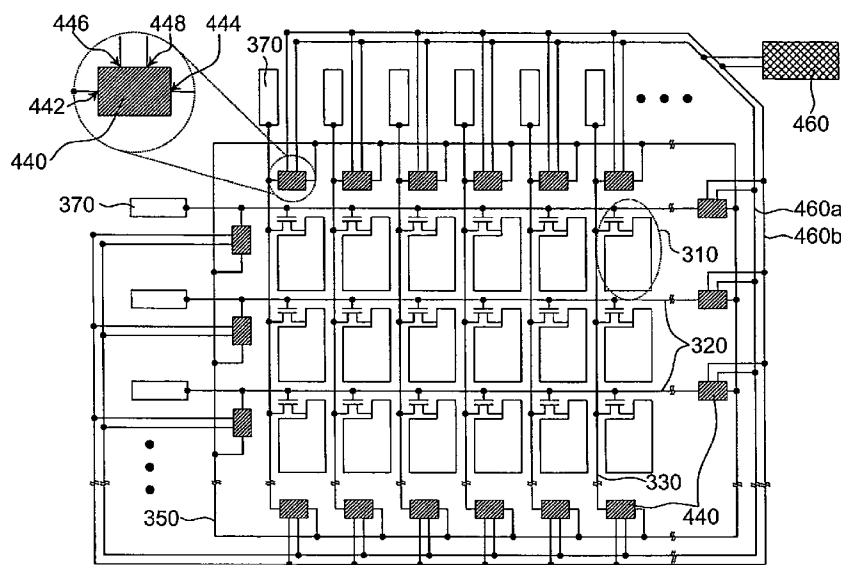
Primary Examiner—Danny Nguyen

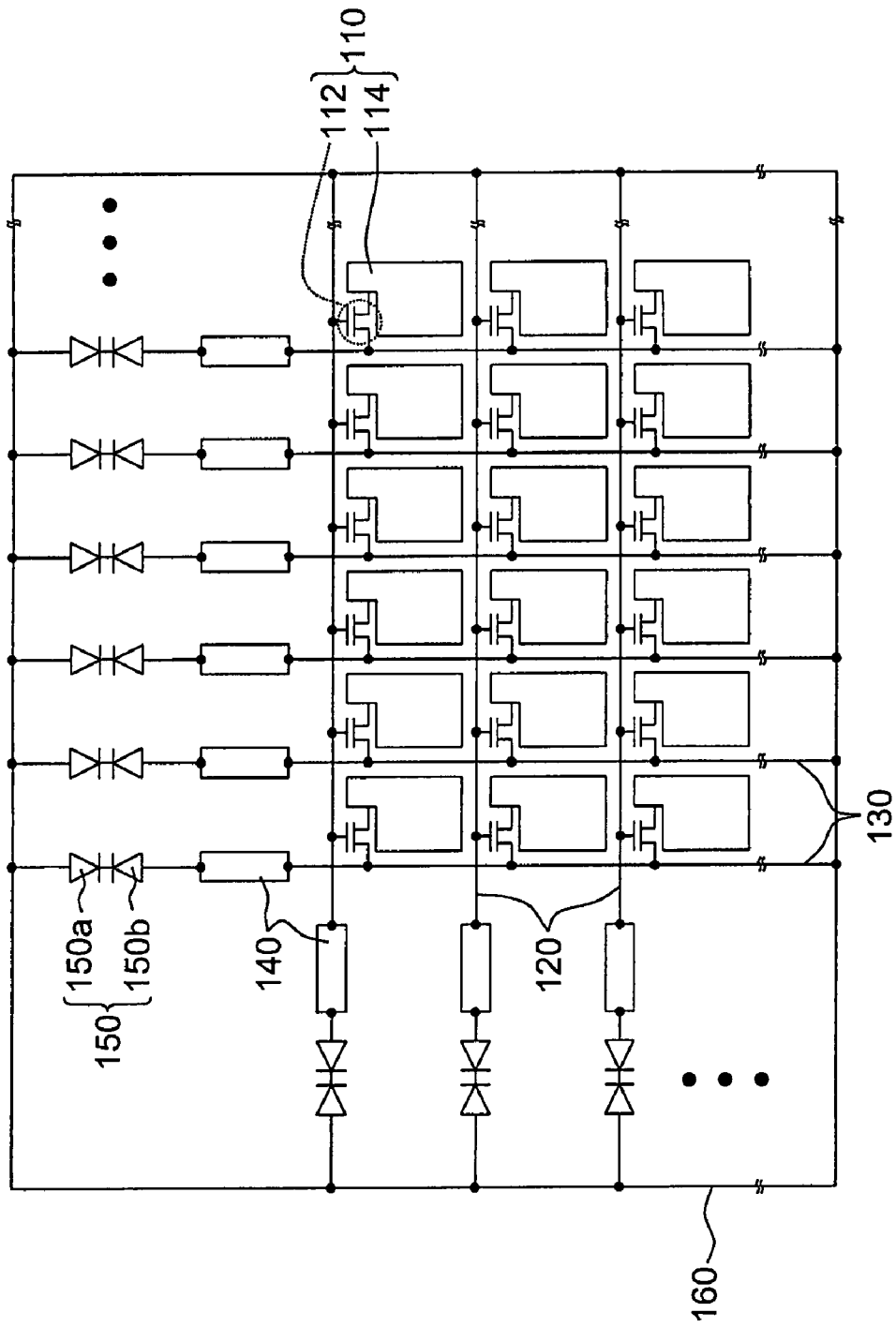
(74) Attorney, Agent, or Firm—Jianq Chyun IP Office

(57) **ABSTRACT**

An active device array substrate includes pixel units, scan lines, data lines, electrostatic discharge (ESD) protection elements, a short ring and an ESD biased generator. Each pixel unit is electrically connected to the corresponding scan line and data line. Each ESD protection element has a first connection terminal, a second connection terminal and a third connection terminal, wherein the first connection terminal is electrically connected to one of the corresponding scan line and data line, the second connection terminal is electrically connected to the short ring, and the third connection terminal is electrically connected to the ESD biased generator. As an ESD stress occurs, the ESD biased generator provides a voltage to the ESD protection elements to turn on them. It causes that the accumulated electrostatic charges are conducted into the lowest potential of the substrate through the short rings, so as to prevent the pixel units from ESD damaging.

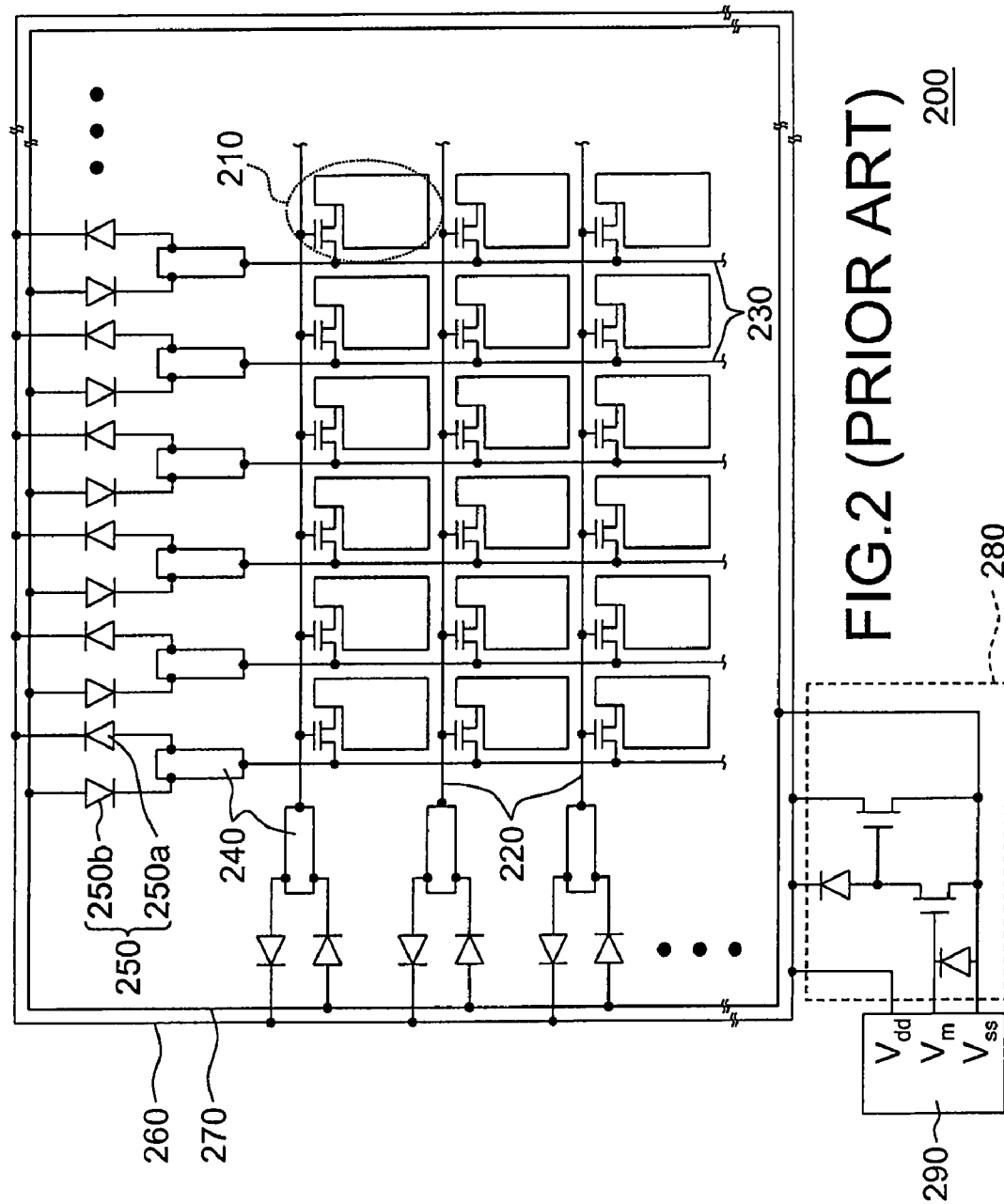
17 Claims, 12 Drawing Sheets





100

FIG.1 (PRIOR ART)



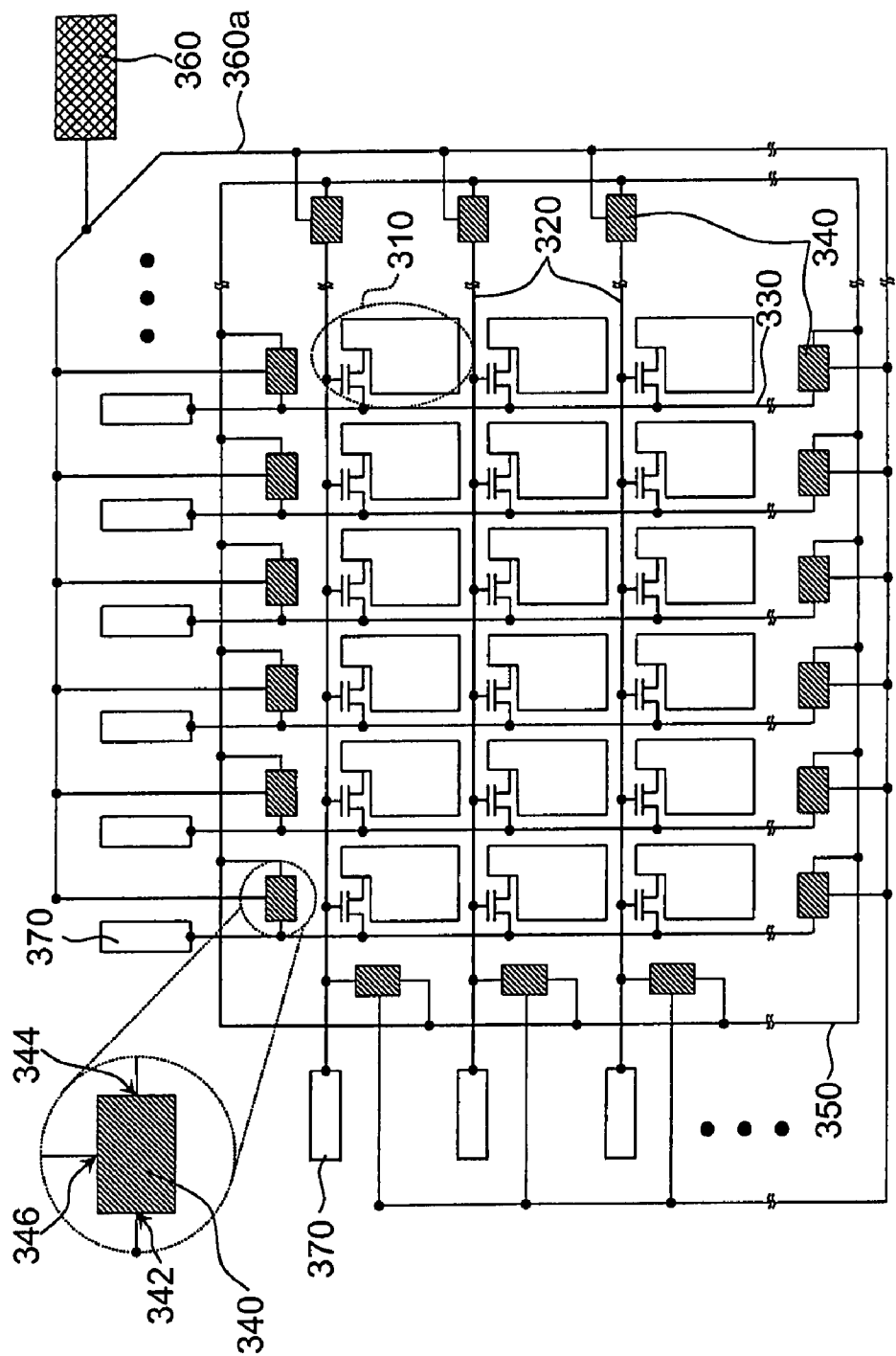


FIG.3

300

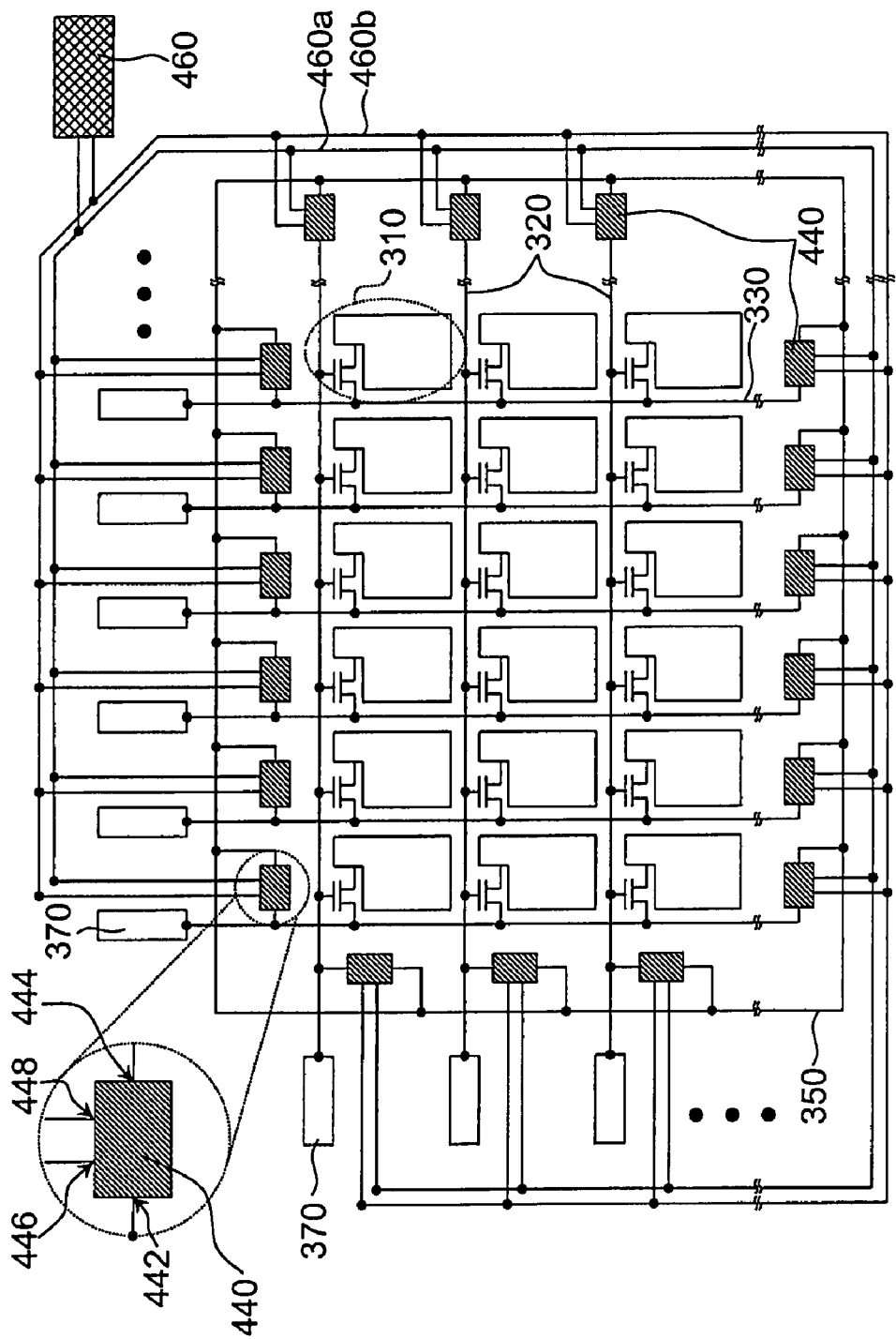


FIG.4

400

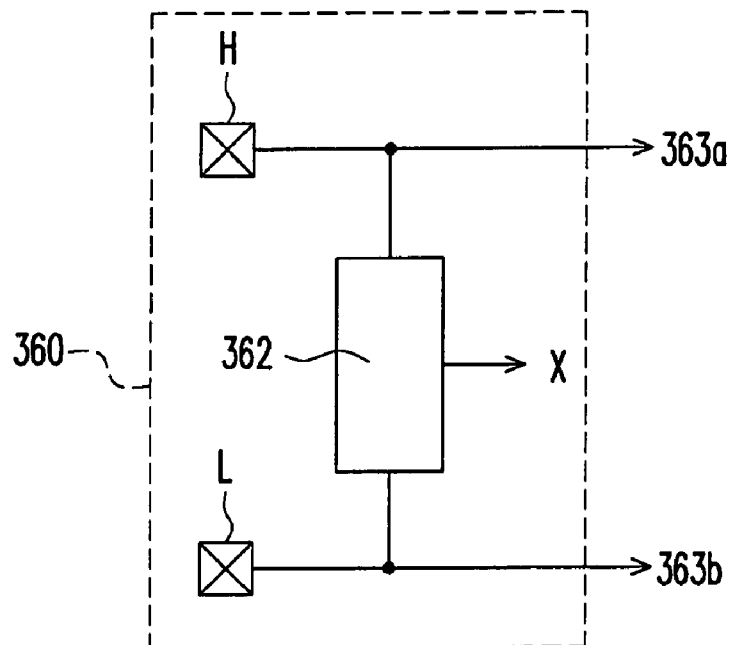


FIG. 5A

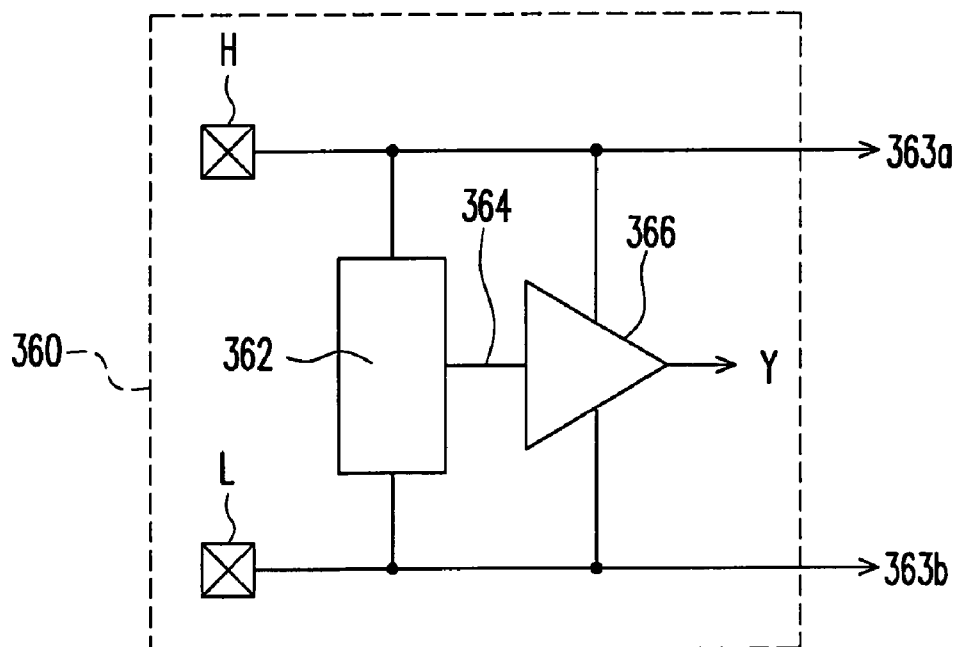


FIG. 5B

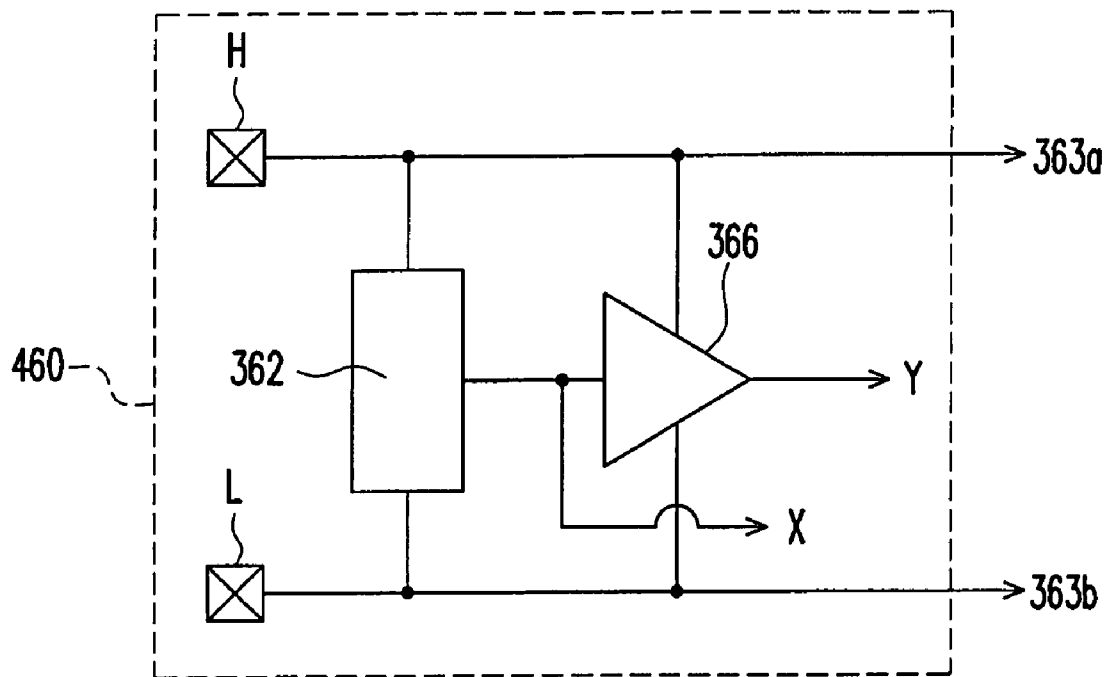


FIG. 5C

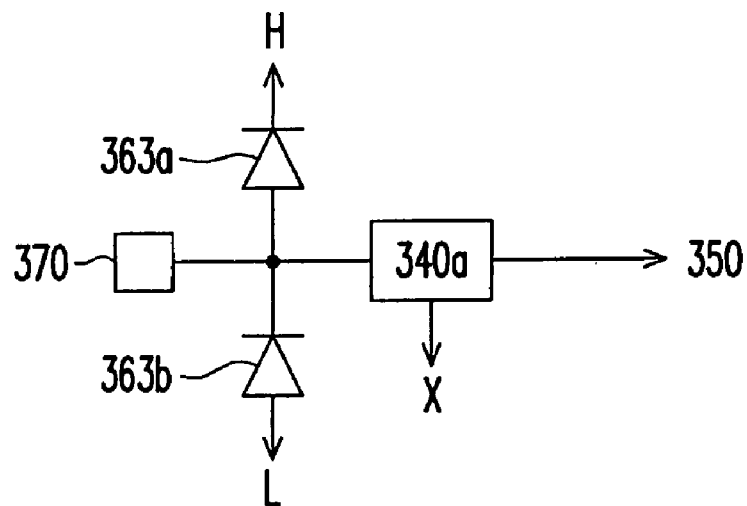


FIG. 6A

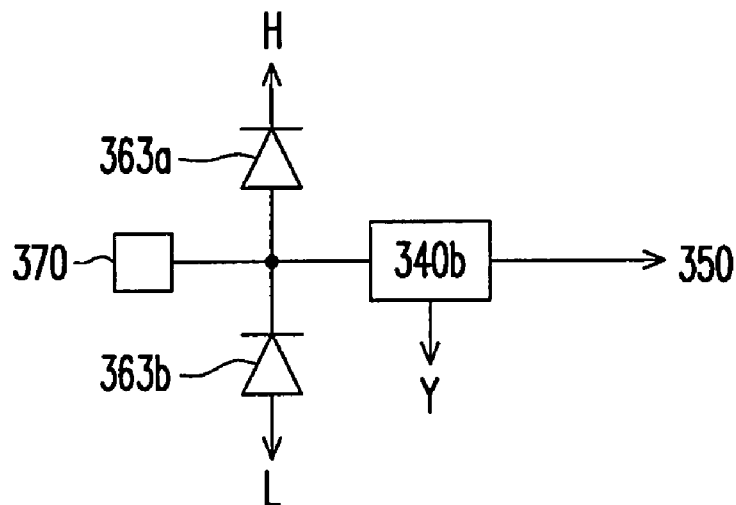


FIG. 6B

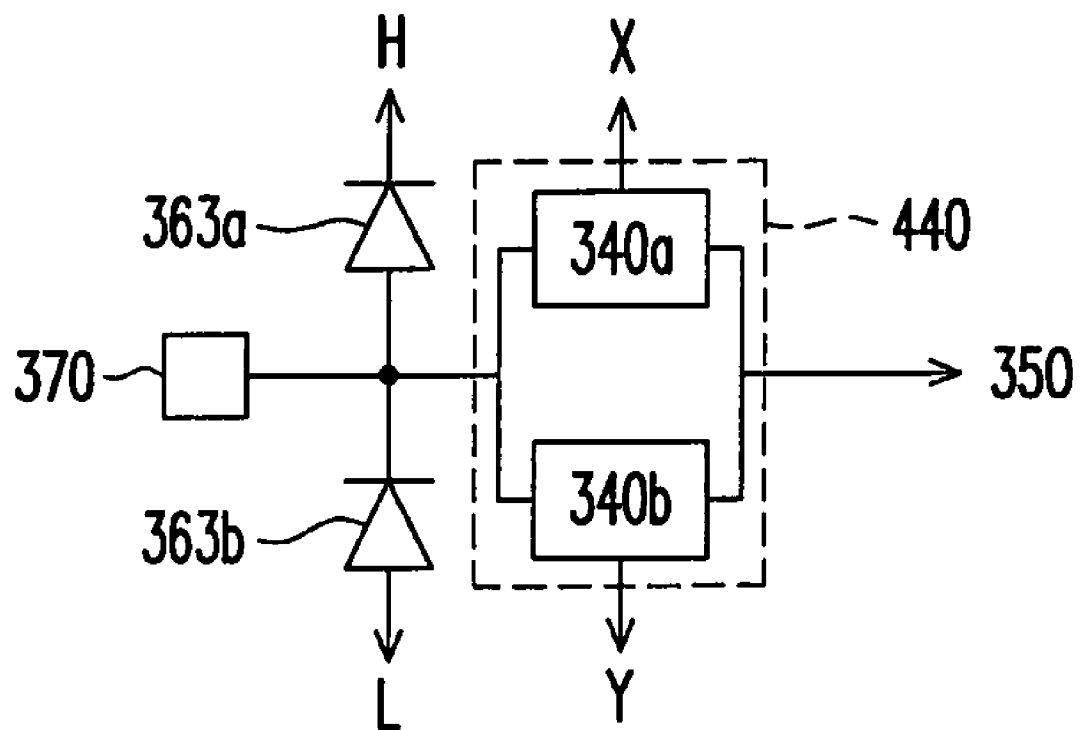


FIG. 6C

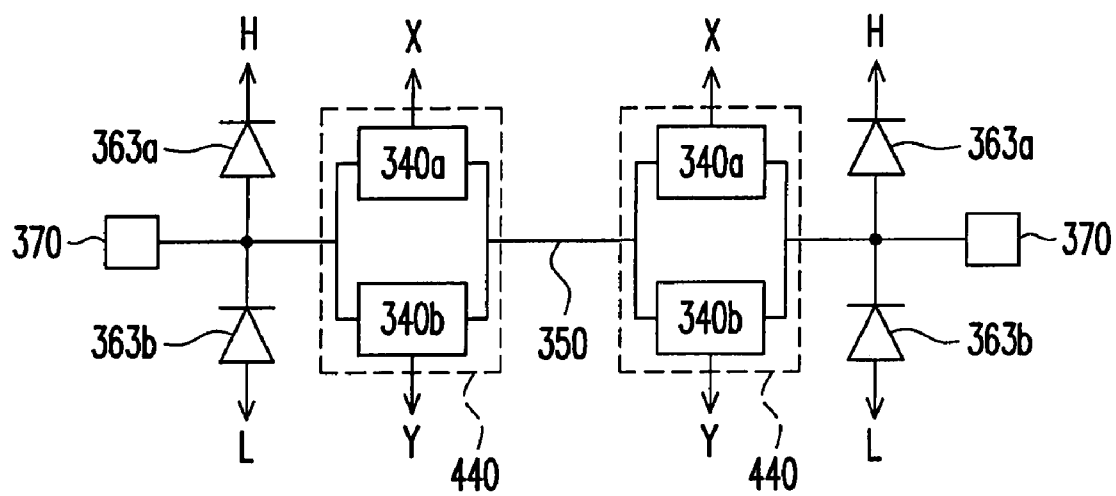


FIG. 7

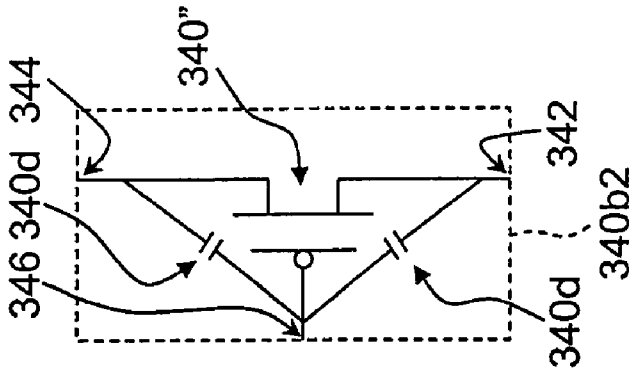


FIG. 8A

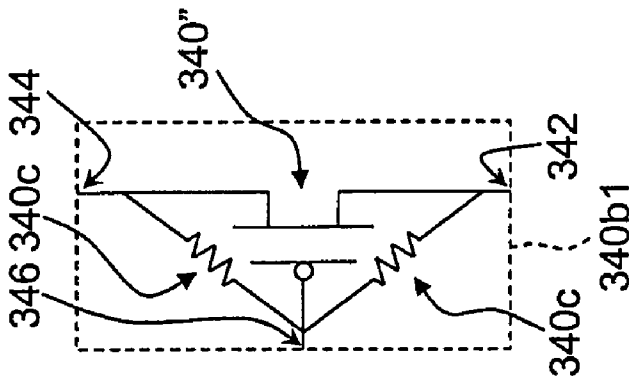


FIG. 8B

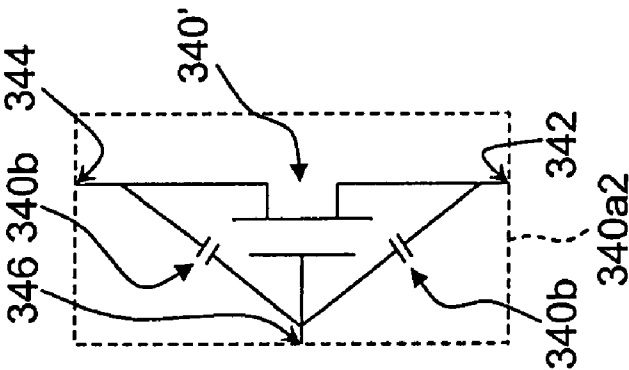


FIG. 8C

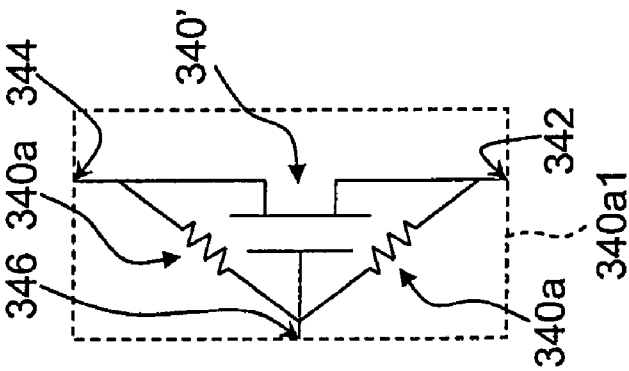


FIG. 8D

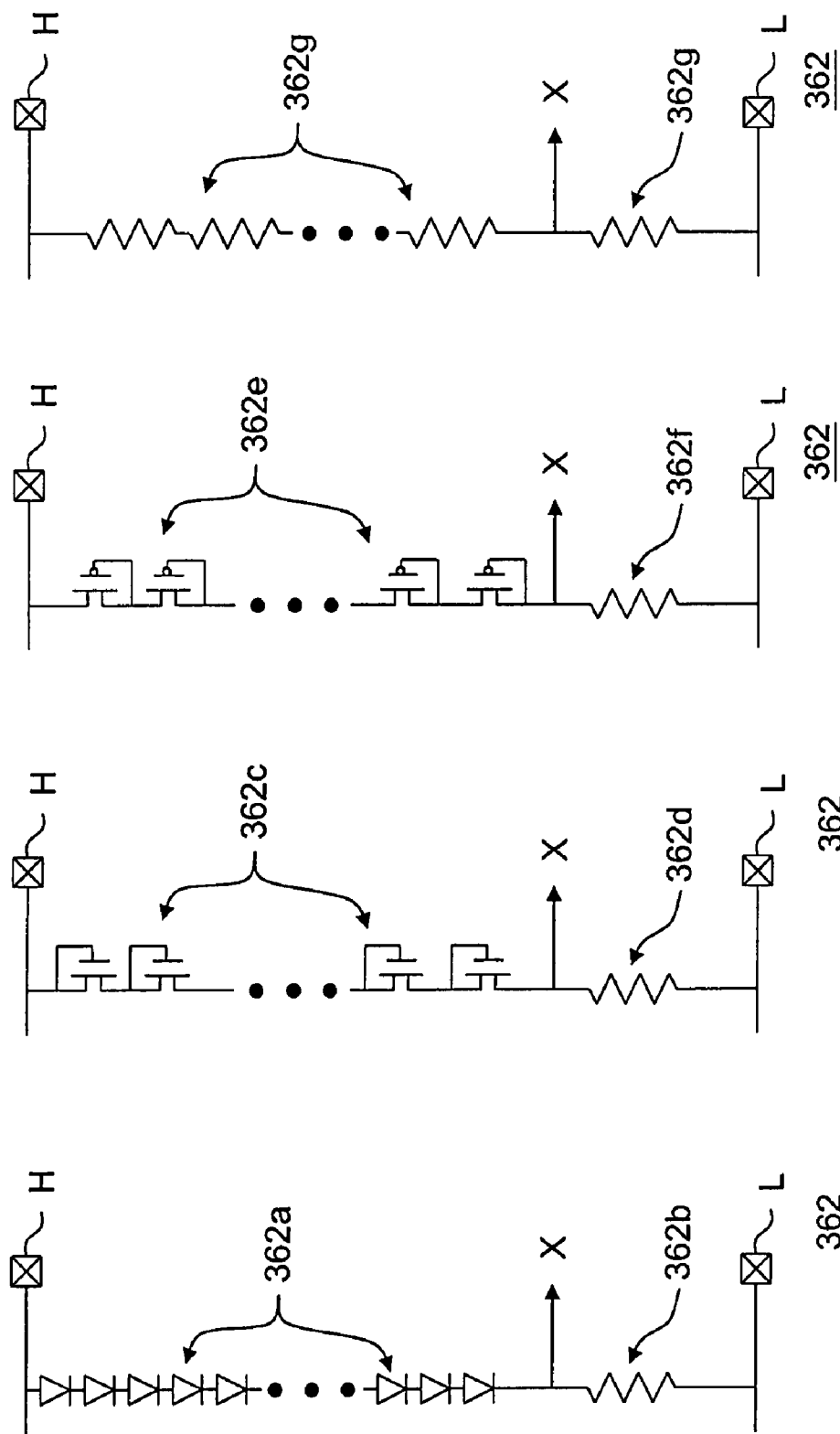


FIG. 9A

FIG. 9B

FIG. 9C

FIG. 9D

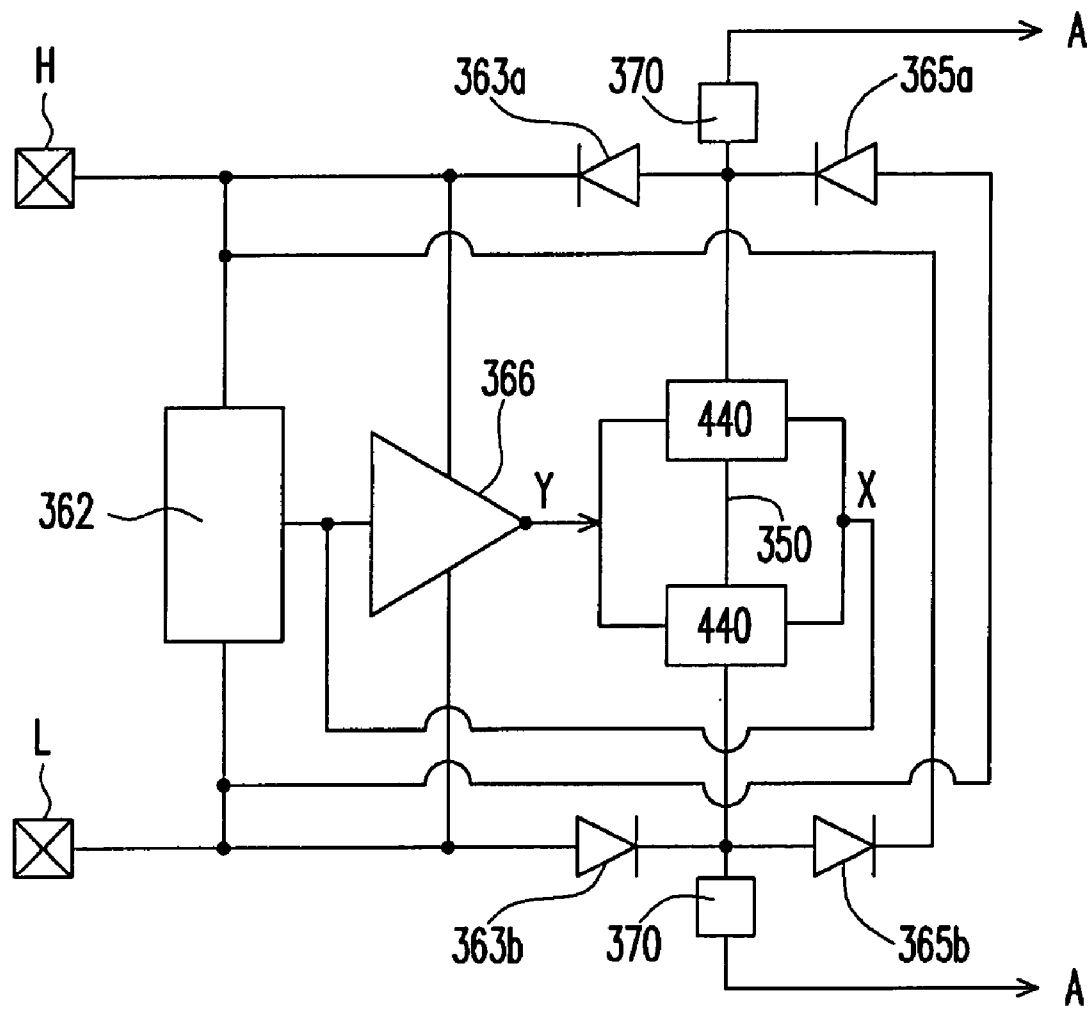


FIG. 10

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ACTIVE DEVICE ARRAY SUBSTRATE HAVING ELECTROSTATIC DISCHARGE PROTECTION CAPABILITY

CROSS-REFERENCE TO RELATED APPLICATION

This application claims the priority benefit of Taiwan application serial no. 95141283, filed Nov. 8, 2006. All disclosure of the Taiwan application is incorporated herein by reference.

BACKGROUND OF THE INVENTION

1. Field of Invention

The present invention relates to an active device array substrate, and particularly to an active device array substrate with an electrostatic discharge (ESD) protection circuit.

2. Description of the Related Art

Along with the modern video technology progress, liquid crystal display (LCD) apparatuses have been largely used as display screens in various electronic products, such as mobile phones, notebook computers, PCs and personal digital assistants (PDAs). In general, an LCD includes a thin film transistor (TFT) array substrate, a color filter substrate and a liquid crystal layer, wherein the TFT array substrate and the color filter substrate are assembled together, and the liquid crystal layer is located between the TFT array substrate and the color filter substrate. By means of all the TFTs in the TFT array substrate to modulate the orientations of the liquid crystal molecules in the liquid crystal layer, the light beam intensity is controlled for displaying images.

During a process for fabricating an LCD apparatus, however, the manufacturing equipment, the operators and the TFT array substrate itself are likely accumulated with a lot of electrostatic discharges, i.e. ESD stressed. Thus, once the TFT array substrate is contacted with the manufacturing equipment, the operators or other charged objects during the production process, an ESD phenomenon is triggered. Due to the fine conductive traces and elements of a TFT array substrate, a minor ESD event often causes a serious result where the affected LCD apparatus is entirely discarded. In order to solve the problem that an ESD event damages an LCD apparatus, a TFT array substrate usually includes an ESD protection circuit.

FIG. 1 is a diagram of a conventional TFT array substrate. Referring to FIG. 1, a conventional TFT array substrate 100 includes pixel units 110, scan lines 120, data lines 130, bonding pads 140, back-to-back diodes 150 and a short ring 160. Each pixel unit 110 includes a TFT 112 and a pixel electrode 114, and the pixel units 110 are arranged in an array are electrically connected to the corresponding scan lines 120 and data lines 130, respectively. An end of each scan line 120 and an end of each data line 130 are electrically connected to the corresponding bonding pads 140, while the bonding pads 140 are electrically connected to the short ring 160 via the corresponding back-to-back diodes 150.

The back-to-back diode 150 has a turned on voltage which is adding up a forward-biased voltage of a diode and a reverse-biased voltage of a diode. When an ESD stress occurs on the TFT array substrate 100, the voltage of the built-up electrostatic charges is usually larger than the turn-on voltage of the back-to-back diode 150 so as to turn on the back-to-back diode 150. Consequently, the electrostatic charges would be conducted to the short ring 160 through the back-to-back diode 150, so as to avoid the electrostatic charges from flowing into the pixel units 110 to damage the TFTs 112. On the

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other hand, during testing the TFT array substrate 100, the testing operation voltage is normally not larger than the turn-on voltage of the back-to-back diode 150, thus an open circuit status is presented between the bonding pad 140 and the short ring 160. That is, there is no interactive voltage influence between the scan line 120 and the data line 130 to affect the normal operations of the pixel units 110.

In order to avoid large current leakage occurs in the back-to-back diode 150 to affect the operation signals between the scan line 120 and the data line 130, it is better that the turned on voltage of the back-to-back diode 150 is larger so as to reduce the effect to the TFT array substrate 100. However, if the turned on voltage of the back-to-back diode 150 is increased, the pixel units 110 are damaged by the ESD charges when the TFT array substrate 100 is subjected to the ESD stress occurred inside or outside the TFT array substrate 100. Therefore, how to design the turned on voltage of the back-to-back diode 150 is important.

After the TFT array substrate 100 is completely fabricated, the wiring circuits between all the bonding pads 140 and the short ring 160 are electrically cut off, following by the subsequent processes. During the successive assembly process however, the TFT array substrate 100 likely accumulates electrostatic charges, and at the point, the TFT array substrate 100 has disabled the ESD protection function already, which puts the TFT array substrate 100 in jeopardy to be damaged by an ESD event.

FIG. 2 is a diagram of another conventional TFT array substrate. Referring to FIG. 2, the conventional TFT array substrate 200 includes pixel units 210, scan lines 220, data lines 230, bonding pads 240, bi-forward diodes 250 and a first short ring 260, a second short ring 270 and a power control circuit 280. The pixel units 210 are electrically connected to the corresponding scan lines 220 and data lines 230, respectively. An end of each scan line 220 and an end of each data line 230 are electrically connected to the corresponding bonding pads 240. Each of the bi-forward diodes 250 includes two diodes 250a and 250b, while the bonding pads 240 are electrically connected to the first short ring 260 via the corresponding diodes 250a and then electrically connected to the second short ring 270 via the corresponding diodes 250b. In addition, the power control circuit 280 is electrically connected to the first short ring 260 and the second short ring 270.

As an ESD event occurs, all of the three voltage levels of the power supply 290 are 0V. When the accumulated electrostatic charges are conducted to the first short ring 260 via the diode 250a or 250b and then conducted to the second short ring 270 through the power control circuit 280, the ESD charges are rapidly transferred to the lowest voltage level on the TFT array substrate 200. Thereby, the accumulated electrostatic charges are neutralized so as to avoid the accumulated electrostatic charges from flowing into the pixel units 210 on the TFT array substrate 200 to cause fatal failure. On the other hand, prior to operating the TFT array substrate 200, a power supply 290 is electrically connected to the ESD protection circuit 280 to provide the ESD protection circuit 280 with a high voltage V_{dd} , a low voltage V_{ss} and a medium voltage V_m . Hence, the ESD protection circuit 280 is able to keep the first short ring 260 in the high voltage V_{dd} and keep the second short ring 270 in the low voltage V_{ss} . Note that the operation voltage for the TFT array substrate 200 is between the high voltage V_{dd} and the low voltage V_{ss} , thus each diode 250a and each diode 250b are reversely biased, which establishes open circuit statuses between the bonding pads 240 and the first short ring 260, and between the bonding pads 240 and the second short ring 270. That is, there is no interactive

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voltage influence between the scan lines **220** and the data lines **230** to affect the normal operations of the pixel units **210**.

In the conventional method, the first and second short ring **260**, **270** are electrically cut off, following by the subsequent processes. During the successive assembly process however, the TFT array substrate **200** likely accumulates electrostatic charges, and at the point, the TFT array substrate **200** has disabled the ESD protection function already, which puts the TFT array substrate **100** in jeopardy to be damaged by an ESD event.

SUMMARY OF THE INVENTION

Based on the above described, the present invention is to provide an active device array substrate having better ESD protection capability.

The present invention provides an active device array substrate, which includes scan lines, data lines, pixel units, ESD protection elements, a first short ring and an ESD biased generator. The pixel units are electrically connected to the corresponding scan lines and data lines, respectively. Each of the ESD protection elements has a first connection terminal, a second connection terminal and a third connection terminal and optionally further has a fourth connection terminal, wherein the first connection terminal is electrically connected to one of the corresponding scan line and data line, the second connection terminal is electrically connected to the short ring, the third connection terminal (and the fourth connection terminal) is/are electrically connected to the ESD biased generator. As an ESD stress occurs, the ESD biased generator would sense the electrostatic voltage and provide a voltage level to the ESD protection elements to turn on them for conducting the accumulated electrostatic charges into the short rings. Thereby, the electrostatic charges are transferred to the lowest voltage level on the active device array substrate and are neutralized, such that the pixel units of the active device array substrate are prevented from damaging.

In one embodiment, the ESD protection element has three connection terminals, and the ESD biased generator comprises a level controller having a node. The node is electrically connected to the third connection terminals of the ESD protection elements.

In one embodiment, the ESD protection element has four connection terminals, and the ESD biased generator comprises a level controller and an inverter having a node. The node is electrically connected to the third connection terminals of the ESD protection elements and an input terminal of the inverter, while an output terminal of the inverter is electrically connected to the fourth connection terminals of the ESD protection elements.

In one embodiment, the level controller comprises at least a diode in forward series and a resistor connected in series to the diode.

In one embodiment, the level controller comprises at least a transistor and a resistor electrically connected to the transistor, and the source electrode of the transistor is electrically connected to the drain electrode of the adjacent transistor and the gate electrode of the transistor is electrically connected to one of the source and drain electrode thereof.

In one embodiment, the level controller comprises at least a resistor in series.

In one embodiment, the ESD protection element comprises an N type transistor. The ESD protection element further comprises two resistors, and the two resistors are electrically connected between the first connection terminal and the third connection terminal, and between the second connection ter-

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minal and the third connection terminal, respectively. In addition, the ESD protection element further comprises two capacitors, and the two capacitors are electrically connected between the first connection terminal and the third connection terminal, and between the second connection terminal and the third connection terminal, respectively.

In one embodiment, the ESD protection element comprises a P type transistor. The ESD biased generator further comprises an inverter electrically connected between the node and the third connection terminals of the ESD protection elements. In addition, the ESD protection element further comprises two resistors, and the two resistors are electrically connected between the first connection terminal and the third connection terminal and between the second connection terminal and the third connection terminal, respectively. Moreover, the ESD protection element further comprises two capacitors, and the two capacitors are electrically connected between the first connection terminal and the third connection terminal and between the second connection terminal and the third connection terminal, respectively.

In summary, as an ESD stress occurs in an active device array substrate of the present invention, the ESD biased generator would sense the electrostatic voltage and provide a voltage level to the ESD protection elements to turn on them for conducting the accumulated electrostatic charges into the short rings. Thereby, the electrostatic charges are transferred to the lowest voltage level on the substrate and are neutralized. In this way, the active device array substrate of the present invention has the desired ESD protection function to avoid the pixel units from damage caused by an ESD.

BRIEF DESCRIPTION OF THE DRAWINGS

The accompanying drawings are included to provide a further understanding of the invention, and are incorporated in and constitute a part of this specification. The drawings illustrate embodiments of the invention and together with the description, and serve for explaining the principles of the invention.

FIG. 1 is a diagram of a conventional TFT array substrate.

FIG. 2 is a diagram of another conventional TFT array substrate.

FIG. 3 is a diagram of an active device array substrate according to an embodiment of the present invention.

FIG. 4 is a diagram of an active device array substrate according to another embodiment of the present invention.

FIGS. 5A-5C are diagrams showing the ESD biased generator.

FIGS. 6A-6C are diagrams showing a connection between one of the bonding pad on the TFT array substrate and the ESD biased generator.

FIG. 7 is diagram showing the ESD protection element and two of the bonding pads on the TFT array substrate.

FIGS. 8A-8D are diagrams of the ESD protection elements in different types provided by the present invention.

FIGS. 9A-9D are diagrams of the level controllers in different types provided by the present invention.

FIG. 10 is a diagram of the local equivalent circuit of the active device array substrate in FIG. 4.

DESCRIPTION OF THE EMBODIMENTS

FIG. 3 is a diagram of an active device array substrate according to an embodiment of the present invention. Referring to FIG. 3, an active device array substrate **300** of the present invention includes a plurality of pixel units **310**, a plurality of scan lines **320**, a plurality of data lines **330**, a

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plurality of ESD protection elements **340**, a short ring **350** and an ESD biased generator **360**. The pixel units **310** are arranged in array and electrically connected to the corresponding scan lines **320** and data lines **330**, respectively. Each of the ESD protection elements **340** has a first connection terminal **342**, a second connection terminal **344**, a third connection terminal **346**, wherein the first connection terminal **342** is electrically connected to one of the corresponding scan line **320** and data line **330**, the second connection terminal **344** is electrically connected to the short ring **350**, the third connection terminal **346** is electrically connected to the ESD biased generator **360**. In more detail, the third connection terminal **346** of each ESD protection elements **340** is electrically connected to a conductive wire **360a**, while the conductive wire **360a** is electrically connected to the ESD biased generator **360**.

The active device array substrate **300** may further include a plurality of bonding pads **370**, and an end of each scan line **320** and each data line **330** are electrically connected to the corresponding bonding pads **370**. In this way, any two bonding pads **370** are electrically connected to each other via two ESD protection elements **340** and the short ring **350**. As the ESD protection elements **340** are turn on, the charges on any bonding pad **370** are able to be quickly conducted to the short ring **350** or other bonding pads **370**, so as to keep a potential balance. In addition, each bonding pad **370** can be further electrically connected to the ESD biased generator **360** via, for example, an ESD protection element.

According to another embodiment of the present invention, the ESD protection element on the active device array substrate can also have four connection terminals. Referring to FIG. 4, the structure of FIG. 4 is similar to FIG. 3, and the different between the two structures is the ESD protection element **440** has a first connection terminal **442**, a second connection terminal **444**, a third connection terminal **446** and a fourth connection terminal **448**. The ESD protection element **440** is a transmission-gate transistor composed of an N type transistor and a P type transistor.

FIG. 5A is diagram showing the ESD biased generator used in the active device array substrate of FIG. 3. Referring to FIG. 5A, the ESD biased generator **360** has a plurality of terminals electrically connected to a high voltage terminal H, a low voltage terminal L and a node X. The ESD biased generator **360** further has a level controller **362** therein. The ESD biased generator **360** is further electrically connected to the diode **363a** and the diode **363b**. Each of the bonding pads **370** on the active device array substrate shown in FIG. 3 is connected to one of the diodes **363a**, **363b**. When an ESD event occurs and a normal operation is performed, the ESD biased generator **360** would generate voltage levels VESD, VOFF on the node X. The diodes **363a**, **363b** are respectively a PIN diode, a PPN diode, a diode connected with an N type transistor or a diode connected with a P type transistor, for example.

In another embodiment, as shown in FIG. 5B, the ESD biased generator **360** has a plurality of terminals electrically connected to a high voltage terminal H, a low voltage terminal L and a node Y. The ESD biased generator **360** further has a level controller **362** and an inverter **366** therein. The ESD biased generator **360** is further electrically connected to the diode **363a** and the diode **363b**. When an ESD event occurs and a normal operation is performed, the ESD biased generator **360** would generate voltage levels VESD' and VOFF' on the node Y.

If the ESD protection element on the active device array substrate has four connection terminals, the used ESD biased generator is as shown in FIG. 5C. Referring to FIG. 5C, the

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ESD biased generator **460** has a plurality of terminals electrically connected to a high voltage terminal H, a low voltage terminal L, a node X and a node Y. The ESD biased generator **460** further has a level controller **362** and an inverter **366** therein. The ESD biased generator **460** is further electrically connected to the diode **363a** and the diode **363b**. When an ESD event occurs and a normal operation is performed, the ESD biased generator **460** would generate voltage levels VESD and VOFF on the node X and generate voltage levels VESD' and VOFF' on the node Y.

In addition, as shown in FIGS. 6A and 6B, any one of the bonding pads **370** on the active device array substrate shown in FIG. 3 is connected to three devices including the diode **363a**, the diode **363b** and the ESD protection element **340a** or **340b**. In an embodiment, as shown in FIG. 6A, the ESD protection element **340a** is connected to the X node of the ESD biased generator **360** (FIG. 5A). In another embodiment, as shown in FIG. 6B, the ESD protection element **340b** is connected to the Y node of the ESD biased generator **360** (FIG. 5B). The ESD protection element **340a** or **340b** is further connected to the short ring **350**. In the case, the diodes **363a**, **363b** would supply a current to the ESD and electrically conduct to the high voltage terminal H and the low voltage terminal L, such that the ESD biased generator would work and the ESD current is channelized by the ESD protection element via the voltage level (VESD and VESD') of the node X and the node Y.

Similarly, if the ESD protection element having four connection terminals are used on the active device array substrate, any one of the bonding pads **370** on the active device array substrate shown in FIG. 4 is connected to three devices including the diode **363a**, the diode **363b** and the ESD protection element **440** composed of the ESD protection elements **340a**, **340b**, as shown in FIG. 6C. Two terminals of the ESD protection element **440** are connected to the node X and the node Y, and the other terminal of the ESD protection element **440** is connected to the short ring **350**. The diodes **363a**, **363b** would supply a current to the ESD and electrically conduct to the high voltage terminal H and the low voltage terminal L, such that the ESD biased generator would work and the ESD current is channelized by the ESD protection element via the voltage level (VESD and VESD') of the node X and the node Y.

In details, as shown in FIG. 7, the ESD protection element having four connection terminals is used. Any two of the bonding pads **370** on the active device array substrate are connected to each other through the ESD protection element **440** (composed of the ESD protection elements **340a**, **340b**) and the short ring **350**. That is, when an ESD event occurs, a voltage is generated on the node X and the node Y through the diodes **363a**, **363b** and the ESD biased generator so as to turn on the ESD protection elements **340a**, **340b**, such that the ESD energy is released via the short ring **350**.

In addition, the ESD protection element of the present invention can be formed of an N type transistor, a P type transistor or a combination thereof. Also, the ESD protection element can also be formed in other types. In the following, other types of the ESD protection element **340** are described in association with the related figures. FIGS. 8A~8D are diagrams of the ESD protection elements in different types provided by the present invention. Referring to FIG. 8A, the ESD protection element **340a1** includes an N-type transistor **340'** and two resistors **340a**. The two resistors **340a** are respectively electrically connected between the first connection terminal **342** and the third connection terminal **346** of the N-type transistor **340'** and between the second connection terminal **344** and the third connection terminal **346** of the

N-type transistor **340'**. That is, the two resistors **340a** are electrically connected between the gate electrode of the N-type transistor **340'** and each of the source and the drain electrode of the N-type transistor **340'**, respectively.

According to other embodiments of the present invention, referring to FIG. 8B, an ESD protection element **340a2** may include an N-type transistor **340'** and two capacitors **340b**. The two capacitors **340b** are respectively electrically connected between the first connection terminal **342** and the third connection terminal **346**, and between the second connection terminal **344** and the third connection terminal **346**. In addition referring to FIG. 8C, another type ESD protection element **340b1** includes a P-type transistor **340''** and two resistors **340c**. The two resistors **340c** are respectively electrically connected between the first connection terminal **342** and the third connection terminal **346**, and between the second connection terminal **344** and the third connection terminal **346**. That is, the two resistors **340c** are electrically connected between the gate electrode of the P-type transistor **340''** and each of the source and the drain electrode of the P-type transistor **340''**, respectively. Furthermore, referring to FIG. 8D, another ESD protection element **340b2** includes a P-type transistor **340''** and two capacitors **340d**. The two capacitors **340d** are respectively electrically connected between the first connection terminal **342** and the third connection terminal **346**, and between the second connection terminal **344** and the third connection terminal **346**.

The level controller **362** of the present invention is described in more detail as follows. FIGS. 9A~9D are diagrams of the level controllers in different types provided by the present invention. Referring to FIG. 9A, the level controller **362** of the present embodiment includes a plurality of diodes **362a** in forward series and a resistor **362b** in series connection to the diodes **362a**, wherein a node X is located between a diode **362a** and the resistor **362b**. When an ESD event occurs and a normal operation is performed, the ESD biased generator **362** would generate voltage levels VESD, VOFF on the node X.

Note that the level controller **362** of the present invention functions to generate a voltage and the above-described embodiment does not limit the construction of the level controller **362** of the present invention. The level controller **362** is described in more detail as follows in association with the related figures. Referring to FIG. 9B, a level controller **362** of the present embodiment includes a plurality of N-type transistors **362c** and a resistor **362d** electrically connected to one of the N-type transistors **362c**, wherein a node X is located between an N-type transistor **362c** and the resistor **362d**. Besides, the source electrode of each N-type transistor **362c** is electrically connected to the drain electrode of the adjacent N-type transistor **362c**, while the gate electrode of each N-type transistor **362c** is electrically connected to the source electrode thereof.

Referring to FIG. 9C, similarly to the above described, another type level controller **362** may include a plurality of P-type transistors **362e** and a resistor **362f** electrically connected to one of the P-type transistors **362e**, wherein a node X is located between a P-type transistor **362e** and the resistor **362f**. Besides, the source of each P-type transistor **362e** is electrically connected to the drain of the adjacent P-type transistor **362e**, while the gate of each P-type transistor **362e** is electrically connected to the drain thereof. Referring to FIG. 9D, another level controller **362** can include a plurality of resistors **362g** in series only, wherein a node X is located between two certain adjacent resistors **362g**.

The ESD protection mechanism on the active device array substrate is described in the following. Generally, when the

ESD stress occurs, there are one position at a high ESD voltage level and one position at a low ESD voltage level on the active device array substrate. The ESD charges always discharge from the high voltage level to the low voltage level. If the ESD protection element is not existed on the active device array substrate, the pixel units will be damaged by the high energy ESD. FIG. 10 is a diagram of the local equivalent circuit of the active device array substrate in FIG. 4. Referring to FIG. 10, when the ESD charges are accumulated to a level and the ESD event occurs on one of the bonding pads **370**, a current is released to the level controller **362** via the diodes **363a** so as to generate a voltage, and a voltage level VESD larger than the threshold voltage of the N type TFT of the ESD protection element **440** is generated at the node X. At the same time, a voltage level VESD' larger than the threshold voltage of the P type TFT is generated at the node Y through the inverter **366**. Thereby, the N type TFT and the P type TFT of the ESD protection element are conducted to each other, such that the ESD charges are conducted to the lowest voltage level on the active array substrate. Moreover, when the active device array substrate is normally operated, which is the active device array substrate is operated with an external applied voltage, the high voltage terminal H and the low voltage terminal L of the ESD biased generator would supply a voltage level and a voltage is formed through the level controller **363**. Then, a voltage level VOFF smaller than the threshold voltage of the N type TFT is generated at the node X, and a voltage level VOFF' smaller than the threshold voltage of the P type TFT is generated at the node Y. Therefore, the N type TFT and the P type TFT of the ESD protection element **440** are turned off. The two bonding pads **370** are open-circuit, such that a current leakage does not happen between the two binding pads **370** when the active device array substrate is normally operated.

In summary, the active device array substrate of the present invention has at least the following advantages:

1. As an ESD stress occurs, the ESD biased generator would sense the electrostatic voltage and provide a voltage to the ESD protection elements to turn on the ESD protection elements, which allows the accumulated electrostatic charges to be quickly conducted to the short ring, thus, an ESD failure to damage the pixel units is avoided.
2. During the active device array substrate is operated, the voltage difference between the two applied voltages can be reduced by adjustment, which contributes to lower the energy consumed by the leakage current and advance the quality of the active device array substrate.

It will be apparent to those skilled in the art that various modifications and variations can be made to the structure of the present invention without departing from the scope or spirit of the invention. In view of the foregoing, it is intended that the specification and examples to be considered as exemplary only, with a true scope and spirit of the invention being indicated by the following claims and their equivalents.

What is claimed is:

1. An active device array substrate, comprising:
 - a plurality of scan lines and a plurality of data lines;
 - a plurality of pixel units, being electrically connected to the corresponding scan lines and data lines, respectively;
 - a plurality of electrostatic discharge (ESD) protection elements, wherein each ESD protection element has a first connection terminal, a second connection terminal and a third connection terminal, and the first connection terminal is electrically connected to one of the corresponding scan line and data line;

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a short ring electrically connected to the second connection terminal of each ESD protection element; and
a conductive wire electrically connected to the third connection terminal of each ESD protection element, wherein the conductive wire is not connected to the short ring;

an ESD biased generator electrically connected to the conductive wire, wherein the ESD biased generator is not directly connected to the short ring, and the conductive wire directly connects with the ESD biased generator and the third connection terminal of each ESD protection element,

wherein, as an ESD stress occurs, the ESD biased generator would sense an electrostatic voltage and provide a voltage to the ESD protection elements to turn on the ESD protection elements, so that the accumulated electrostatic charges are conducted to the short ring.

2. The active device array substrate as recited in claim 1, wherein the ESD biased generator comprises a level controller having a node, and the node is electrically connected to the third connection terminals of the ESD protection elements.

3. The active device array substrate as recited in claim 2, wherein the level controller comprises at least a diode in forward series and a resistor connected in series to the diode.

4. The active device array substrate as recited in claim 2, wherein the level controller comprises at least a transistor and a resistor electrically connected to the transistor, and the source electrode of the transistor is electrically connected to the drain electrode of the adjacent transistor and the gate electrode of the transistor is electrically connected to one of the source and drain electrode thereof.

5. The active device array substrate as recited in claim 2, wherein the level controller comprises at least a resistor in series.

6. The active device array substrate as recited in claim 1, wherein the ESD protection element comprises an N type transistor, a P type transistor or a combination thereof.

7. The active device array substrate as recited in claim 6, wherein the ESD protection element further comprises two resistors, and the two resistors are electrically connected between the first connection terminal and the third connection terminal, and between the second connection terminal and the third connection terminal, respectively.

8. The active device array substrate as recited in claim 6, wherein the ESD protection element further comprises two capacitors, and the two capacitors are electrically connected between the first connection terminal and the third connection terminal, and between the second connection terminal and the third connection terminal, respectively.

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9. The active device array substrate as recited in claim 2, wherein the ESD protection element comprises an N type transistor, a P type transistor or a combination thereof, and the ESD biased generator further comprises an inverter electrically connected between the node and the third connection terminals of the ESD protection elements.

10. The active device array substrate as recited in claim 9, wherein the ESD protection element further comprises two resistors, and the two resistors are electrically connected between the first connection terminal and the third connection terminal, and between the second connection terminal and the third connection terminal, respectively.

11. The active device array substrate as recited in claim 9, wherein the ESD protection element further comprises two capacitors, and the two capacitors are electrically connected between the first connection terminal and the third connection terminal, and between the second connection terminal and the third connection terminal, respectively.

12. The active device array substrate as recited in claim 9, wherein each ESD protection element further comprises a fourth connection terminal electrically connected to the ESD biased generator.

13. The active device array substrate as recited in claim 12, wherein the ESD biased generator comprises a level controller and an inverter having a node, and the node is electrically connected to the third connection terminals of the ESD protection elements and an input terminal of the inverter, while an output terminal of the inverter is electrically connected to the fourth connection terminals of the ESD protection elements.

14. The active device array substrate as recited in claim 13, wherein the level controller comprises at least a diode in forward series and a resistor connected in series to the diode.

15. The active device array substrate as recited in claim 13, wherein the level controller comprises at least a transistor and a resistor electrically connected to the transistor, and the source electrode of the transistor is electrically connected to the drain electrode of the adjacent transistor and the gate electrode of the transistor is electrically connected to one of the source and drain electrode thereof.

16. The active device array substrate as recited in claim 13, wherein the level controller comprises at least a resistor in series.

17. The active device array substrate as recited in claim 12, wherein the ESD protection element comprises a transmission-gate transistor.

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